

# High Speed LED Mounting Machine SMT Pick And Place Machine With 40000CPH 10 Heads

## **Basic Information**

- Place of Origin:
- Brand Name:
- Certification:
- Model Number:
- Minimum Order Quantity:
- Price:
- Packaging Details:
- Delivery Time:
- Payment Terms:
- Supply Ability:



### Product Specification

Place Of Origin:	China
Name:	YT-101S
Mounting Height:	<36mm
Dimension:	3150*2250*1650mm
Total Weight:	2000kg
Power:	380AC 50HZ
• Power Consumption:	8KW
Mounting Speed:	80000CPH
Warranty:	1 Year
Visual Camera:	2 Sets Of Imported Camera
Drive Way:	High-end Magnetic Linear Motor +se Motor
Highlight:	LED Mounting Machine High Speed, LED Mounting Machine 40000CPH, 10 Head Pick And Place Machine

CHINA

ETON

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ccc,ce,risa YT-101S

L/C, T/T

FOB USD 46000/sets

30 days after deposit

50 sets per mouth

Our packing is made of wooden box with vacuum package, and we promise to deliver the goods within four weeks after payment.

# led lamp manufacturing machinery high speed led mounting machine led assembly machine smt pick and place machine smt production process

#### Features of SMT pick and place machine

**YT-101 SMT placement machine with high speed Multi Modular heads** Apply high speed multi modular head, apply to ultra small chip 0201~40\*40mm large Chip, wider component range.

#### YT-101 smt placement machine with Brand new flight vision Camera

Improve recognition performance, size up to 40\*40mm , apply to BGA or CSP etc.

#### YT-101 SMT placement machine with Vasuum Sensing Device and Ultra high speed capacity

Each placement head with independent detection function, which improves the stability of the equipment and the reliability of the product.

Adopt high-end magnetic linear motor, servo system and multi function modular head, the capacity increased by 25% compared qith traditional machine, optimum placement speed reach 40000CPH.

#### Pictures of pick and place machine





# ETON HORNOR SERIES YT101S



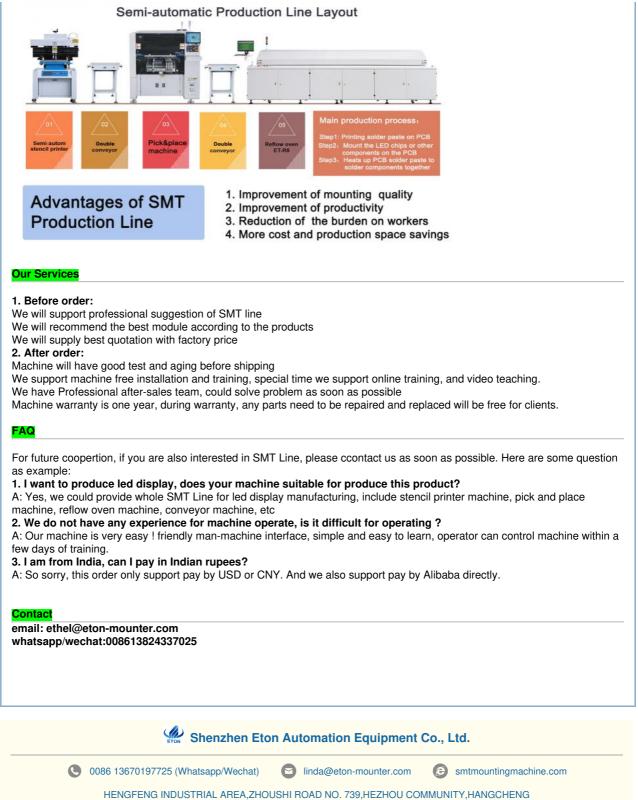
#### SMT PRODUCTION LINE SOLUTION

The surface mount assembly process mainly includes the following steps: solder paste printing, component mount, and reflow soldering. The steps are summarized as follows:

Stencil Printing: solder paste is a follow-up material for the surface adhesive components and PCB to connect with each other. First, the steel plate is etched or laser cut, and then the solder paste is printed on the welding pad of PCB by the squeegee of the Printing machine, so as to enter the next step.

Component Placement: Component Placement is the key technology and work focus of the entire SMT process. The process USES highly precise automatic mounting equipment to accurately place the surface mount components on the solder pad of the printed PCB through computer programming. As the design of surface adhesive components is becoming more and more precise, the distance between the joints is becoming smaller, so the technical level difficulty of placement operation is increasing day by day.

**Reflow Soldering,** (Reflow Soldering) : Reflow Soldering is to have been placed on the surface of adhesive components of the PCB, after Reflow furnace first preheating with activated flux, to raise its temperature to 217 melt solder paste, feet and PCB Soldering pad connected components, then after cooling, cooling, make the solder curing, surface adhesive components and PCB bonding is completed.



STREET, BAOAN, SHENZHEN, CHINA